

IN THE SPECIFICATION:

Please replace paragraph [0029] with the following amended paragraph:

[0029] Processing cell 300 also includes a heating source configured to increase the temperature of the substrate during a fluid processing step. The heating source may include a heated fluid source 375 in fluid communication with the fluid dispensing arm 350 and/or the backside nozzles 308. The source of heated fluid 375 may include a fluid tank having a resistive heating element 380 [[382]] positioned therein. The heating Heating element 380 is in electrical communication with a source of power 382. The source of power 382 may be in communication with controller 111, and as such, be controlled by controller 111 illustrated in FIG. 1. The fluid tank may be in fluid communication with another tank or supply, such as a deionized water supply, that is configured to supply fresh rinsing fluid to the fluid tank. Other fluid sources that may be in communication with the fluid tank include cleaning solutions, etching solutions, and/or other solutions that may be useful in an electrochemical plating process, such as acids, peroxides, and mixtures thereof. One exemplary solution may be a combination of an acid and peroxide, which is generally used to conduct a bevel etching process in semiconductor processing. Further, the source of heated fluid 375 may include a fluid temperature measuring device, e.g., a thermocouple 381, positioned in the tank to measure the temperature of the fluid in the fluid tank. The thermocouple 381 may be in electrical communication with the system controller 111, and as such, the system controller 111 may be used to control the temperature of the fluid in the fluid tank by controlling the operation of the heating element 380 in accordance with data received from the thermocouple 381 and/or a processing recipe. Therefore, the source of heated fluid 375 may be generally configured to maintain a fluid solution therein at a predetermined temperature.